

Figure 1

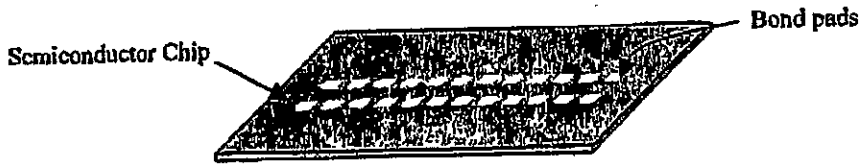


Figure 2

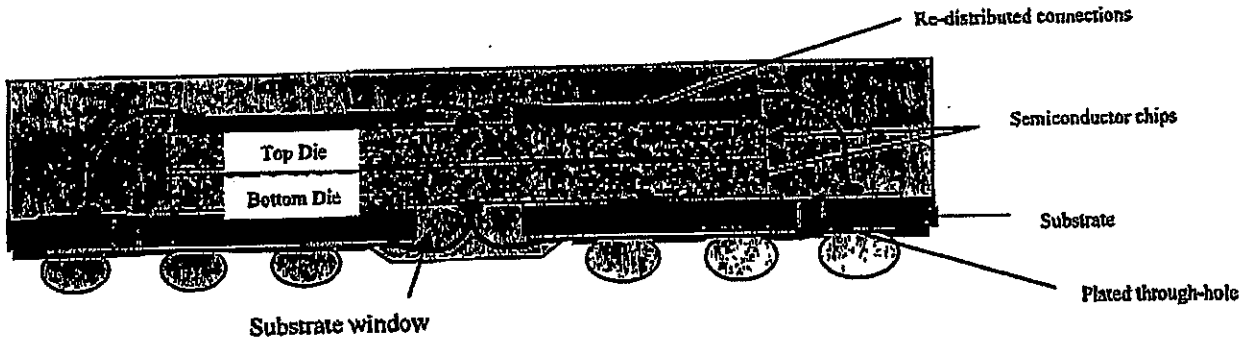


Figure 3

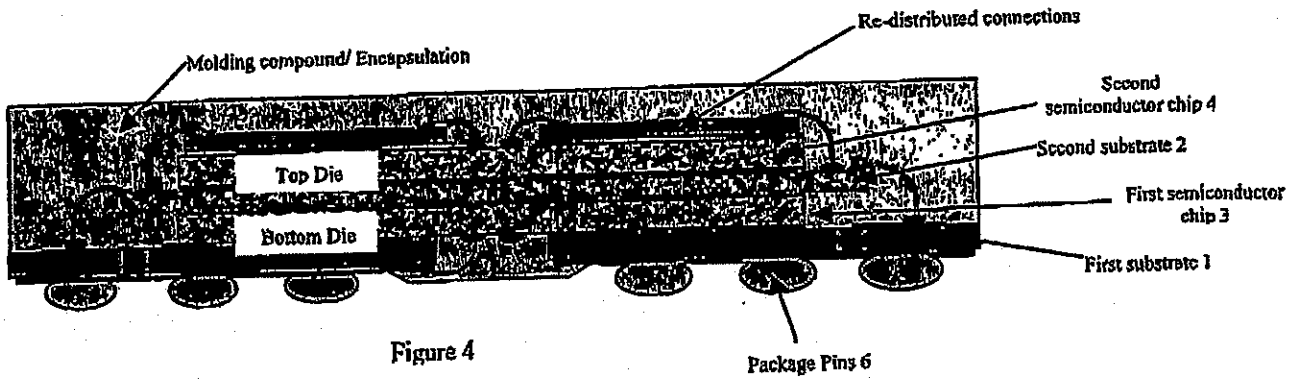


Figure 4

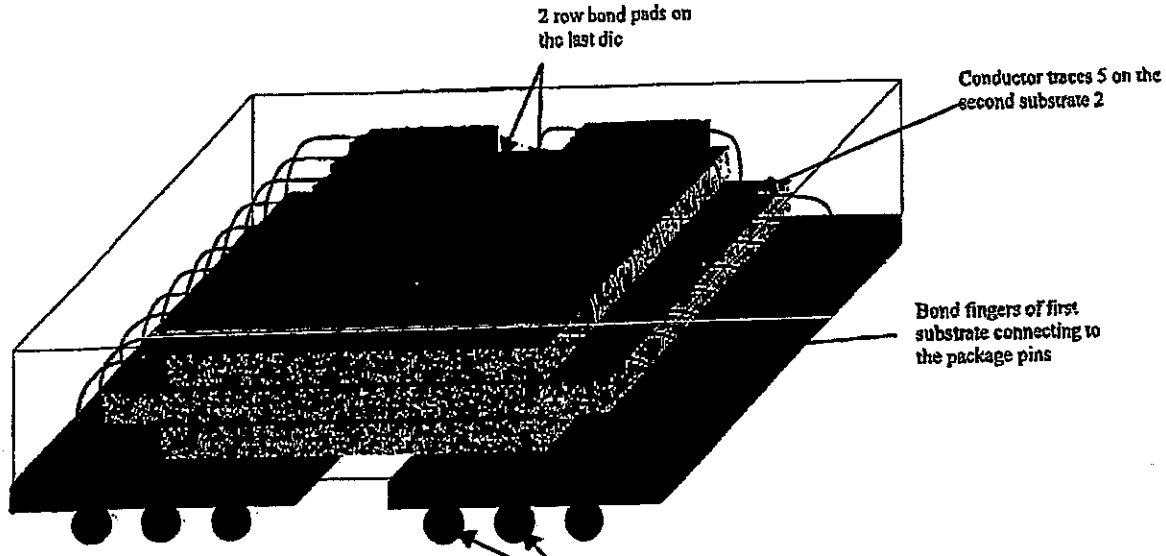


Figure 5

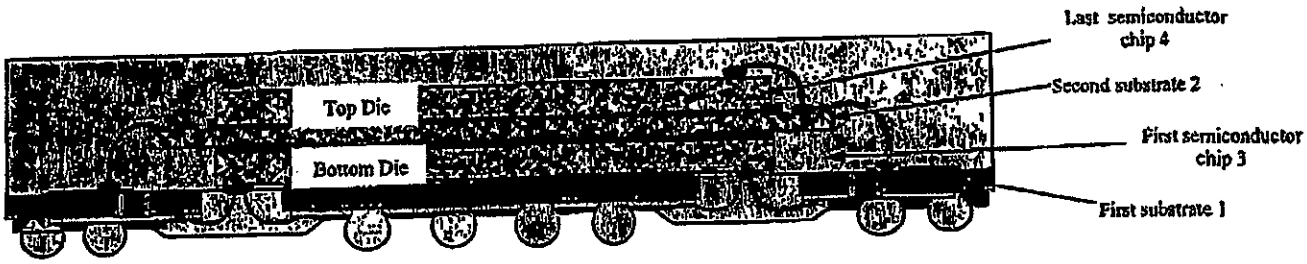


Figure 6

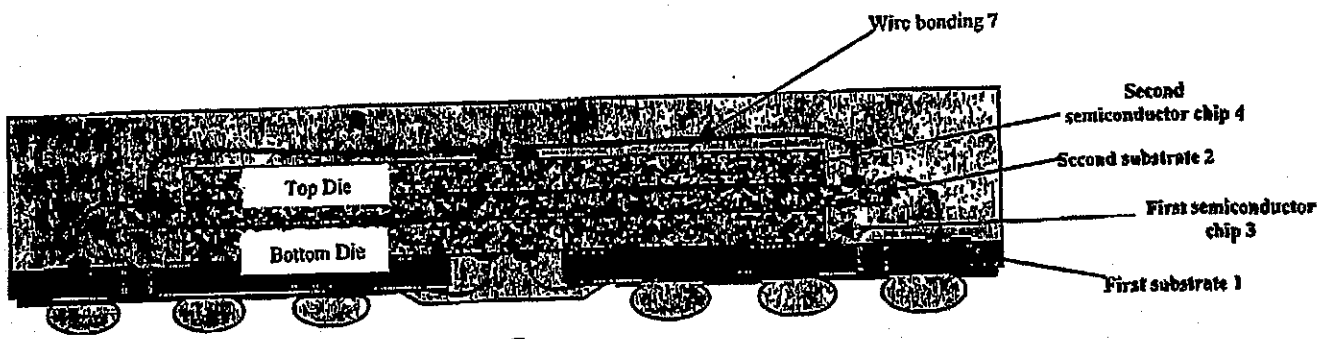


Figure 7

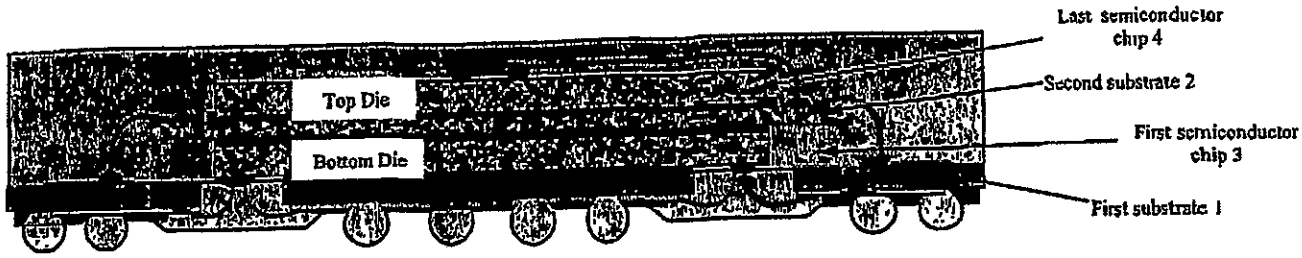


Figure 8

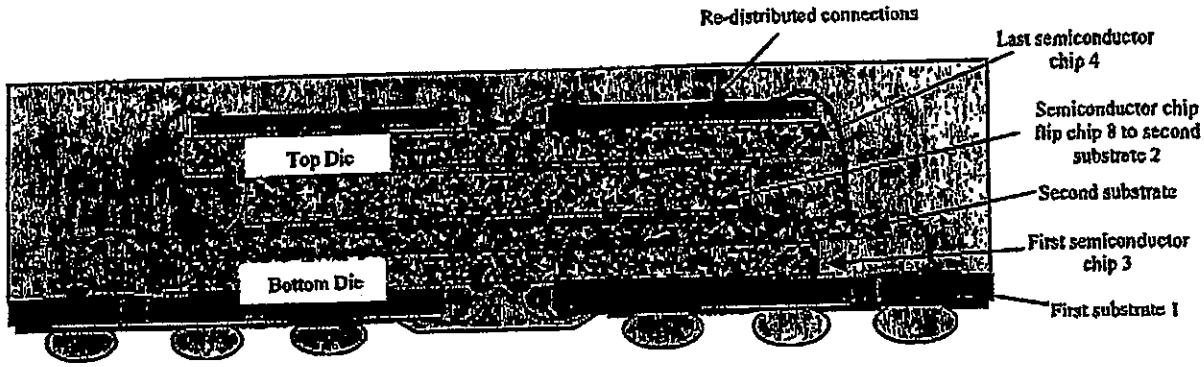


Figure 9

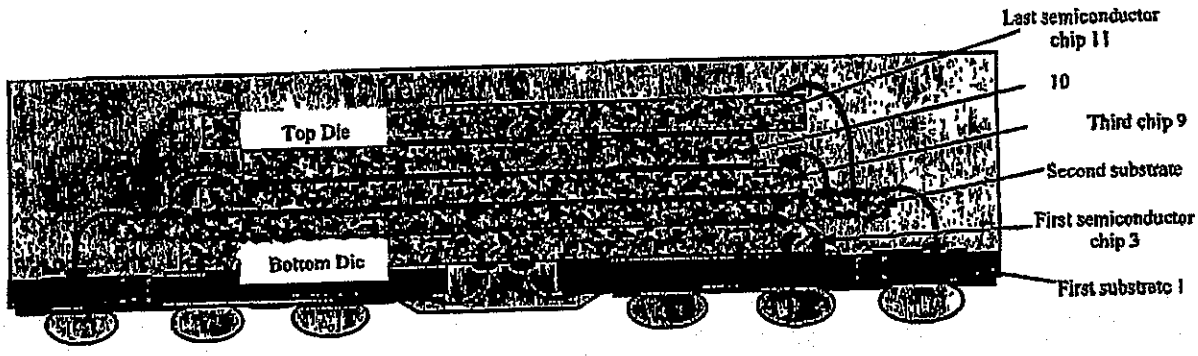


Figure 10

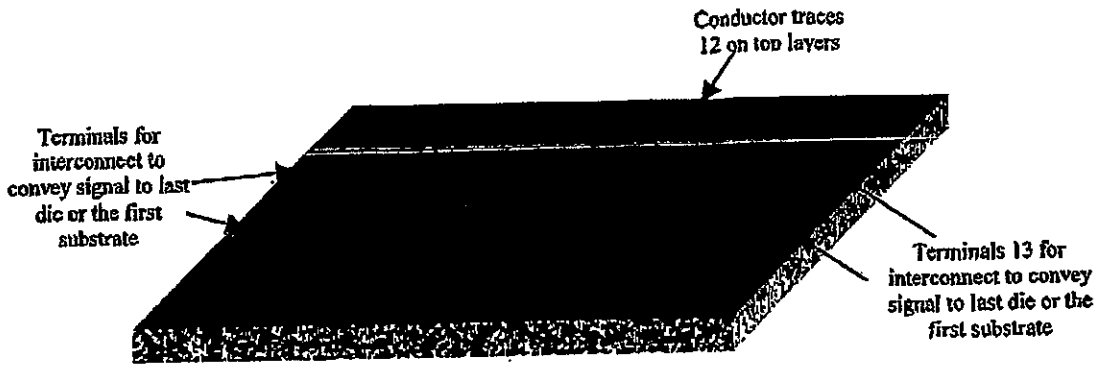


Figure 11A

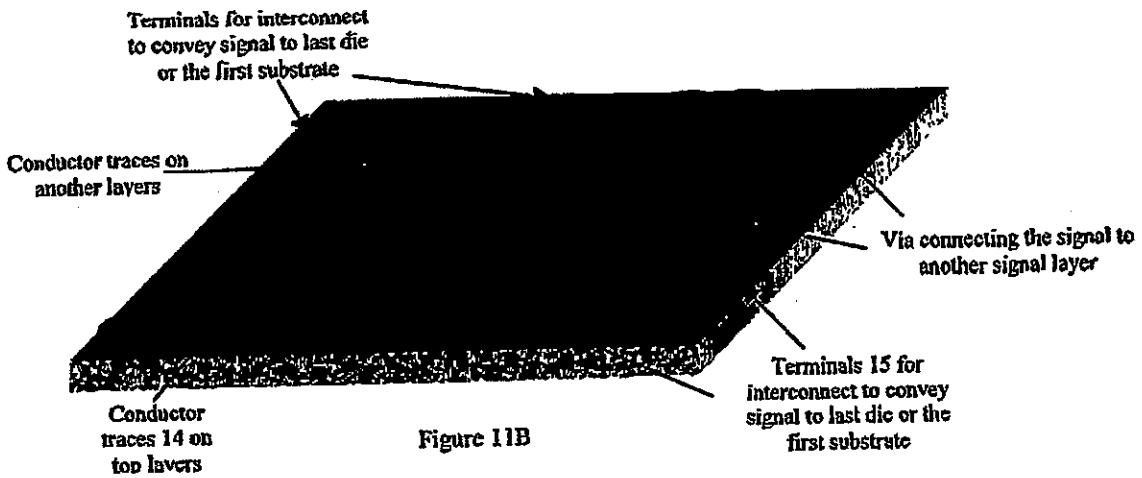


Figure 11B

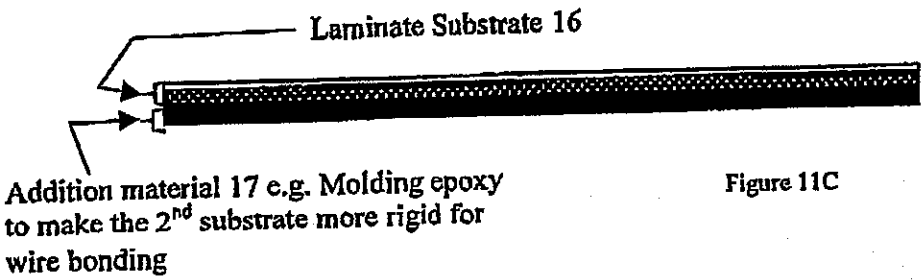


Figure 11C

Figure 12: Method of Manufacture (1/2)

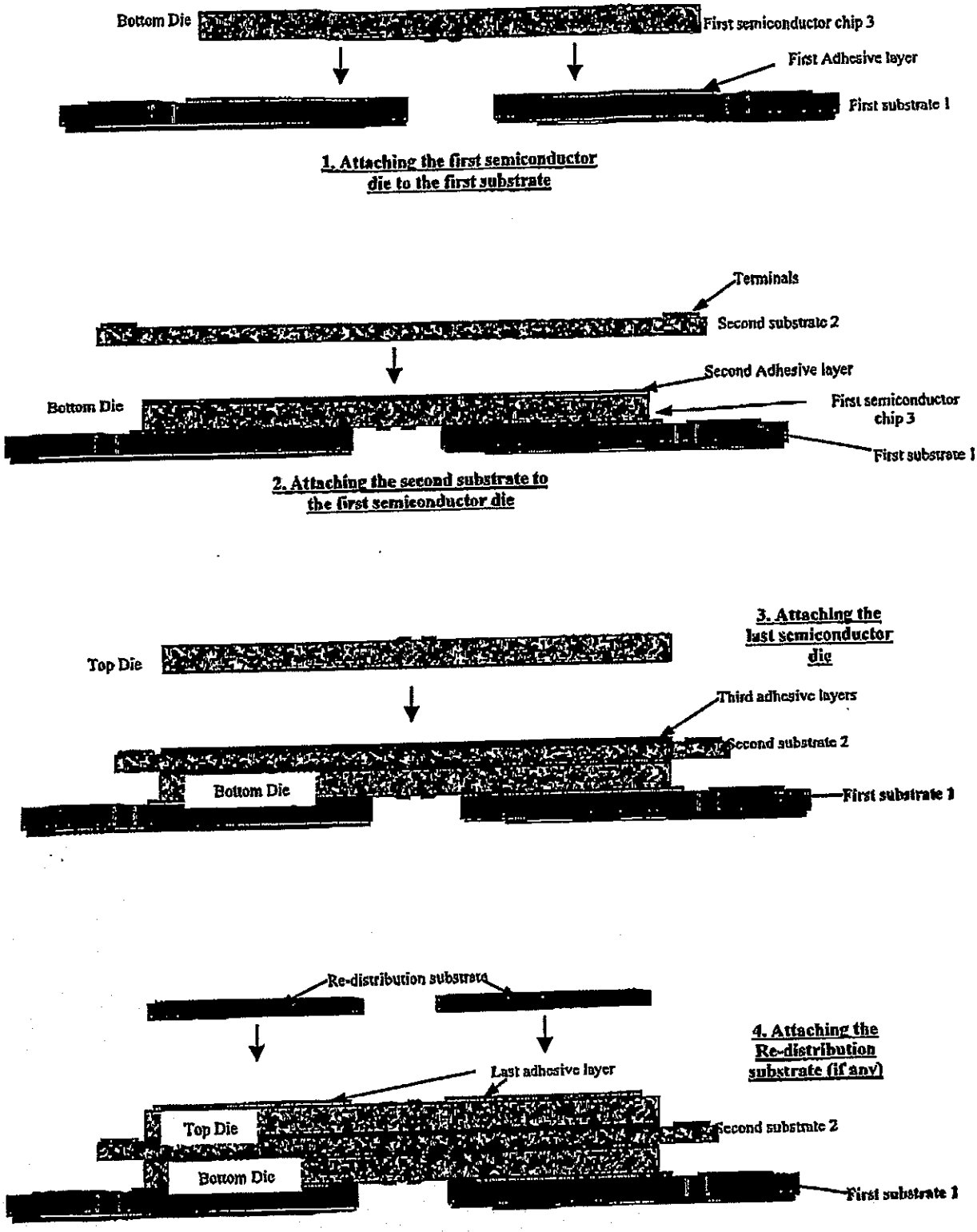
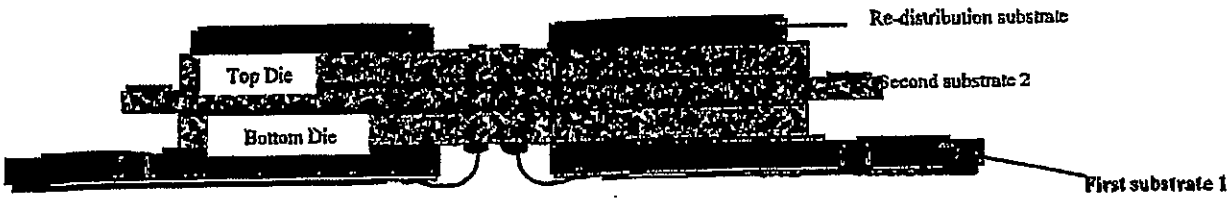
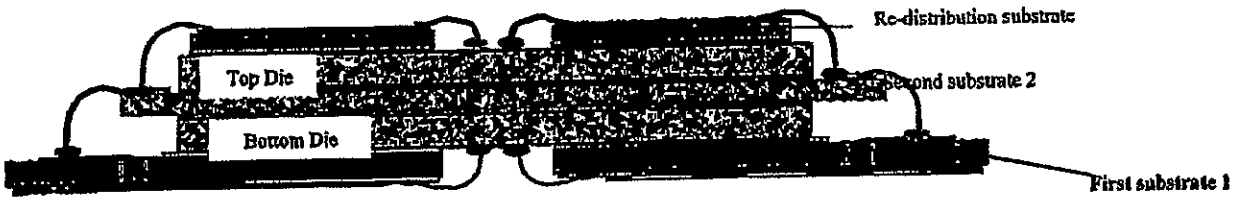


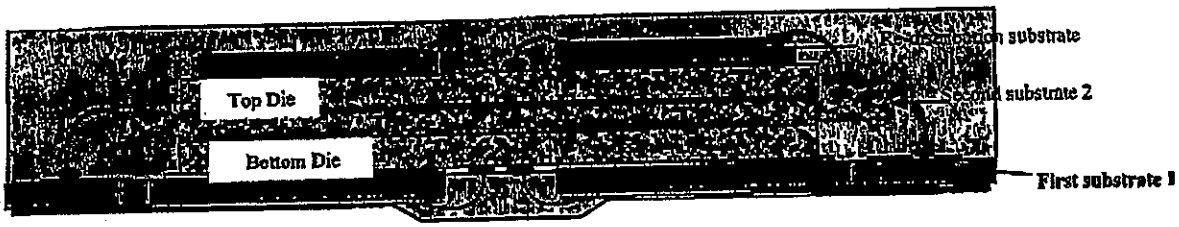
Figure 12: Method of Manufacture (2/2)



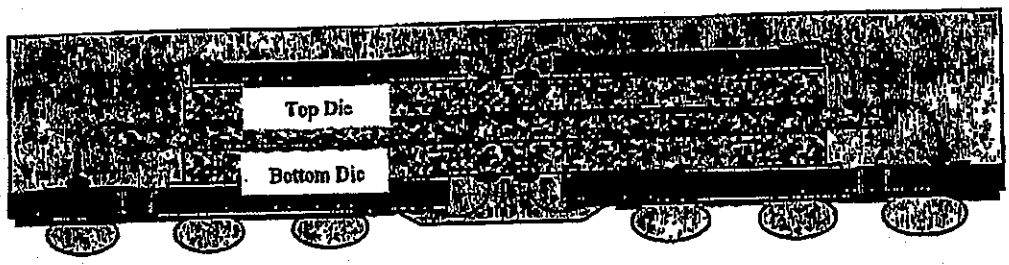
5. Wire bonding to the first semiconductor die

6. Wire bonding on the die side of the first substrate





7. Transfer molding on both the die side and solder ball side of the first substrate at the same time



8. Solder ball attach to the first substrate